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[^0]
## Features

- Low Power Loss GreenBridge ${ }^{\text {TM }}$ Replaces Diode Bridge
- Self Driving Circuitry for MOSFETs
- Low $\mathrm{r}_{\mathrm{DS}(\text { on })} 80 \mathrm{~V}$ Rated MOSFETs
- Maximizing Available Power and Voltage
- Eliminating Thermal Design Problems
- IEEE802.3at Compatible
- Meet Detection and Classification Requirement
- Work with 2 and 4-pair Architecture
- Small Backfeed Voltage

■ Compact MLP 4.5x5 Package

## Applications

■ Power over Ethernet (PoE) Power Device (PD)

- IP Phones
- Network Cameras
- Wireless Access Points
- Thin Clients
- Microcell
- Femtocell


## General Description

FDMQ8205 is GreenBridge ${ }^{T M} 2$ series of quad MOSFETs for a bridge application so that the input will be insensitive to the polarity of a power source coupled to the device. Many known bridge rectifier circuits can be configured using typical diodes. The conventional diode bridge has relatively high power loss that is undesirable in many applications. Especially, Power over Ethernet (PoE) Power Device (PD) application requires high-efficiency bridges because it should be operated with the limited power delivered from Power Source Equipment (PSE) which is classified by IEEE802.3at. FDMQ8205 is configured with low $r_{\text {DS(on) }}$ dual P-ch MOSFETs and N-ch MOSFETs so that it can reduce the power loss caused by the voltage drop, compared to the conventional diode bridge. FDMQ8205 enables the application to maximize the available power and voltage and to eliminate the thermal design problems in PoE PD applications.

FDMQ8205 GreenBridge ${ }^{\text {TM }} 2$ is compatible with IEEE802.3at PoE standard by not compromising detection and classification requirement as well as small backfeed voltage.

## Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
| :---: | :---: | :---: | :---: | :---: | :---: |
| FDMQ8205 | FDMQ8205 | MLP4.5x5 | 13 " | 12 mm | 3000 units |

## Typical Application



Figure 1. Typical Application of Power Device for Power over Ethernet

## Block Diagram



Figure 2. Block Diagram

Pin Configuration


Figure 3. Pin Assignment (Bottom View)

Pin Descriptions

| Pin Number | Name | Description |
| :--- | :--- | :--- |
| 1 | G1 | Gate of Q1 N-ch MOSFET |
| 4 | G2 | Gate of Q2 P-ch MOSFET |
| 9 | G3 | Gate of Q3 P-ch MOSFET |
| 12 | G4 | Gate of Q4 N-ch MOSFET |
| 13,14 | INPUT1 | Input1 of GreenBridge ${ }^{\text {TM }}$ |
| 15,16 | INPUT2 | Input2 of GreenBridge ${ }^{\text {TM }}$ |
| $2,3,11,10$ | OUTN | Negative Output of GreenBridge $^{\text {TM }}$ |
| $5,6,7,8$ | OUTP | Positive Output of GreenBridge ${ }^{\text {TM }}$ |

Notes:

1. Show the feature that provides orientation or pin 1 location.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

|  |  |  | Min. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| INPUT1, INPUT2 to OUTN |  |  |  | 80 | V |
| OUTP to INPUT1, INPUT2 |  |  |  | 80 | V |
| INPUT1 to INPUT2 |  |  |  | 80 | V |
| INPUT2 to INPUT1 |  |  |  | 80 | V |
| OUTP to OUTN |  |  |  | 80 | V |
| G1, G2, G3, G4 to OUTN |  |  |  | 70 | V |
| OUTP to G1, G2, G3, G4 |  |  |  | 70 | V |
| $\mathrm{V}_{\text {G_TRANSIENT }}$ | Transient Gate Voltage, Puls Duty Cycle < 0. | $\text { th < } 200 \mu \mathrm{~s} \text {, }$ |  | 100 | V |
| Continuous $\mathrm{I}_{\text {INPUT }}$ (GreenBridge ${ }^{\text {TM }}$ Current, Q1+Q3 or Q2+Q4) | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | (Note 2a) |  | 3.0 | A |
|  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | (Note 2b) |  | 1.7 | A |
| Pulsed $\mathrm{I}_{\text {INPUT }}(\mathrm{Q} 1+\mathrm{Q} 3$ or Q2+Q4) | Pulse Width < $300 \mu \mathrm{~s}$, Duty C | 2\% (Note 3) |  | 58 | A |
| $\mathrm{P}_{\mathrm{D}}($ Power Dissipation, Q1+Q3 or Q2+Q4) | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | (Note 2a) |  | 2.5 | W |
|  | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | (Note 2b) |  | 0.78 | W |
| Max Junction Temperature |  |  |  | 150 | ${ }^{\circ} \mathrm{C}$ |

Notes:
2. $R_{\theta J A}$ is determined with the device mounted on a $1 \mathrm{in}^{2}$ pad 2 oz copper pad on a $1.5 \times 1.5 \mathrm{in}$. board of FR-4 material. $R_{\theta J C}$ is guaranteed by design while $R_{\theta C A}$ is determined by the user's board design.

3. Pulse Id measured at $\mathrm{td}<=300 \mu \mathrm{~s}$, refer to SOA graph for more details.

## Thermal Characteristics

| Symbol | Parameter | Min. | Typ. | Max. | Units |  |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{R}_{\text {ӨJC }}$ | Thermal Resistance, Junction to Case |  | 5.1 |  |  |  |
| $\mathrm{R}_{\text {ӨJA }}$ | Thermal Resistance, Junction to Ambient | (Note 2a) |  | 50 |  |  |
| $\mathrm{R}_{\theta \text { JA }}$ | Thermal Resistance, Junction to Ambient | (Note 2b) |  | 160 |  |  |

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Conditions | Min. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {InPut }}$ | Input Voltage of Bridge | INPUT1 to INPUT2 or INPUT2 to INPUT1 |  | 57 | V |
| $V_{G}$ | Gate Voltage of MOSFETs | G1, G4 to OUTN G2, G3 to OUTP |  | 57 | V |
| İnput | Input Current of Bridge | Bridge Current through Q2 and Q4 or (Q3 and Q1) |  | 1.7 | A |
| Ambient Operation Temperature ( $\mathrm{T}_{\mathrm{A}}$ ) |  |  | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |
| Junction Operating Temperature ( $\mathrm{T}_{\mathrm{J}}$ ) (Note 5) |  |  | -40 | 125 | ${ }^{\circ} \mathrm{C}$ |

## Electrical Characteristics

Unless otherwise noted: $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {InPUT }}$ | Input Voltage of Bridge | At INPUT1 to INPUT2 or INPUT2 to INPUT1 |  |  | 57 | V |
| $\mathrm{V}_{\mathrm{G}}$ | Gate Voltage of MOSFETs | At G1, G4 to OUTN and G2, G3 to OUTP |  |  | 57 | V |
| $\mathrm{I}_{\mathrm{Q}}$ | Quiescent Current | Detection Mode $1.5 \mathrm{~V}<\mathrm{V}_{\text {INPUT }}=\mathrm{V}_{\mathrm{G}}<10.1 \mathrm{~V} \quad$ (Note 4) |  |  | 5 | $\mu \mathrm{A}$ |
|  |  | Classification Mode $10.2 \mathrm{~V}<\mathrm{V}_{\text {INPUT }}=\mathrm{V}_{\mathrm{G}}<23.9 \mathrm{~V} \quad$ (Note 4) |  |  | 400 | $\mu \mathrm{A}$ |
|  |  | Power On Mode <br> Maximum $\mathrm{V}_{\text {INPUT }}=\mathrm{V}_{\mathrm{G}}=57 \mathrm{~V}$ <br> (Note 4) |  |  | 3.2 | mA |
| VTURN_ON | Turn-On Voltage of MOSFETs | Turn-On of MOSFETs while $\mathrm{V}_{\mathrm{G}}$ Increases (Note 4) | 32 |  | 36 | V |
| I Leakage | Turn-Off Leakage Current | $\begin{aligned} & \mathrm{V}_{\text {OUTP }}=57 \mathrm{~V}, \mathrm{~V}_{\text {OUTN }}=0 \mathrm{~V} \\ & \mathrm{~T}_{\mathrm{J}}=-40^{\circ} \mathrm{C} \text { to } 85^{\circ} \mathrm{C} \end{aligned}$ <br> (Note 4) |  |  | 700 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\mathrm{BF}}$ | Backfeed Voltage | $\mathrm{V}_{\text {OUTP }}=57 \mathrm{~V}, \mathrm{~V}_{\text {OUTN }}=0 \mathrm{~V}, 100 \mathrm{kOhm}$ between INPUT1 and INPUT2 <br> $\mathrm{T}_{\mathrm{J}}=-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ <br> (Note 4) |  |  | 2.7 | V |
| $\mathrm{r}_{\text {DS(on) }}$ | N-ch MOSFET | $\mathrm{V}_{\mathrm{G}}=42 \mathrm{~V}, \mathrm{I}_{\text {INPUT }}=1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 35 | 51 | $\mathrm{m} \Omega$ |
|  |  | $\mathrm{V}_{\mathrm{G}}=48 \mathrm{~V}, \mathrm{I}_{\text {INPUT }}=1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 29 | 44 | $\mathrm{m} \Omega$ |
|  |  | $\mathrm{V}_{\mathrm{G}}=57 \mathrm{~V}, \mathrm{l}_{\text {INPUT }}=1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 26 | 37 | $\mathrm{m} \Omega$ |
|  | P-ch MOSFET | $\mathrm{V}_{\mathrm{G}}=-42 \mathrm{~V}, \mathrm{I}_{\text {INPUT }}=-1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 95 | 147 | $\mathrm{m} \Omega$ |
|  |  | $\mathrm{V}_{\mathrm{G}}=-48 \mathrm{~V}, \mathrm{I}_{\text {INPUT }}=-1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 83 | 125 | $\mathrm{m} \Omega$ |
|  |  | $\mathrm{V}_{\mathrm{G}}=-57 \mathrm{~V}, \mathrm{I}_{\text {INPUT }}=-1.5 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 76 | 107 | $\mathrm{m} \Omega$ |

Notes:
4. INPUT1 is connected to G3 and G4 and also INPUT2 is connected to G1 and G2 like below.


[^1]Typical Characteristics (Q1 or Q4 N-Channel) $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted.


Figure 4. Normalized On Resistance vs. Junction Temperature



Figure 5. Source to Drain Diode Forward Voltage vs. Source Current

Figure 6. Gate Leakage Current vs. Gate to Source Voltage

Typical Characteristics (Q2 or Q3 P-Channel) $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted.


Figure 7. Normalized On Resistance vs. Junction Temperature



Figure 8. Source to Drain Diode Forward Voltage vs. Source Current

Figure 9. Gate Leakage Current vs. Gate to Source Voltage

Typical Characteristics ( Q1 + Q3 or Q2 + Q4 In Serial) $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted.


Figure 10. Forward Bias Safe Operating Area


Figure 11. Single Pulse Maximum Power Dissipation


Figure 12. Junction-to-Ambient Transient Thermal Response Curve


Figure 13. Leakage vs. Output Voltage Curve



#### Abstract

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[^1]:    5. Backfeed Voltage can not be guaranteed for junction temperature in excess of $85^{\circ} \mathrm{C}$. See $\mathrm{V}_{\mathrm{BF}}$ in Electrical Characteristics Table.
